

容量—電圧特性から推定した high-k/InGaAs MOS キャパシタの酸化膜トラップ分布

Determination of oxide traps distribution in high-k/InGaAs MOS capacitor by capacitance-voltage measurement

東工大フロンティア研¹, 東工大総理工², 〇寶春萌¹,角嶋邦之², 片岡好則², 西山彰², 杉井信之², 若林整², 筒井一生¹, 名取研二¹, 岩井洋¹Tokyo Tech. FRC¹, IGSSE², 〇C. Dou¹, K. Kakushima², Y. Kataoka²,A. Nishiyama², N. Sugii², H. Wakabayashi², K. Tsutsui², K. Natori¹, H. Iwai¹E-mail: dou.c.aa@m.titech.ac.jp

Introduction: To realize high performance III-V based n-MOSFETs, a crucial issue arousing increasing attention is the existence of large amounts of oxide traps near or above the conduction band minima, which may degrade on-state performance of the devices severely [1]. In this study, we propose a method to determine the distribution of oxide traps in energy and space by an empirical model to evaluate the frequency (f) and temperature (T) dependent response of oxide traps using the equations summarized in Table I.

Model description: The time constant of oxide traps, τ_{bt} , can be given by Eq. 1 [2], where τ_0 is the time constant at the interface, κ is the tunneling decay factor and x is the distance from the interface into the oxide. τ_0 can be given by Eq. 2, where N_C is density of conduction band states, σ is the capture cross-section and v_{th} is the thermal velocity. The temperature dependency of τ_0 is inferred to be dominated by thermal activated σ governed by Eq. 3 [3], where σ_0 is the pre-factor and E_b is the activation energy. Therefore, the temperature and frequency dependent probing depth, X_p , can be given by Eq. 4. Adopting commonly used parameters for In_{0.53}Ga_{0.47}As, the X_p at 100 Hz and 1 MHz as a function of temperature is shown in Fig. 1.

Results and discussion: X_p decreases with increasing frequency or decreasing temperature. In the 100 Hz to 1 MHz C-V measurement (Fig. 1), while the response of the oxide traps reside in Region I/III is too fast/slow to be detected, the oxide traps in Region II contribute to the frequency dispersion of the C-V curves in accumulation. Therefore, the temperature dependent frequency dispersion in accumulation actually reflects the spatial distribution of oxide traps. A method to profile the oxide traps is proposed and the result is shown in Fig. 2. .

Reference: [1] M. Heyns, et al., *IEDM*, pp. 299-302 (2011). [2] F. P. Heiman, et al, *IEEE Trans. Electron Devices*, vol. ED-12, no. 4 (1965). [3] D. K. Schroder, *Semiconductor Material and Device Characterization*, New York : Wiley (2006).

Table I. Summary of the equations used to evaluate the probing depth:

Time constant of border traps:	
$\tau_{bt} = \tau_0 e^{2\kappa(E)x}$	Eq. (1)
$\tau_0 \approx (N_C \sigma v_{th})^{-1}$	Eq. (2)
Temperature dependency of σ:	
$\sigma = \sigma_0 \exp\left(-\frac{E_b}{kT}\right)$	Eq. (3)
Evaluation of probing depth:	
$X_p = \frac{1}{2\kappa} \ln \frac{1}{2\pi f \tau_0}$	Eq. (4)

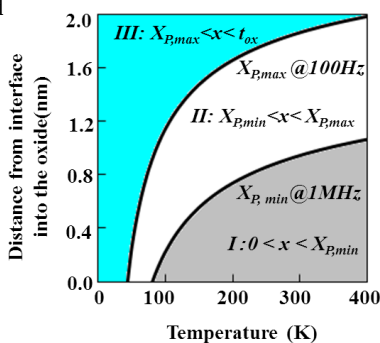


Fig. 1. Probing depth at 100 Hz and 1 MHz as a function of temperature

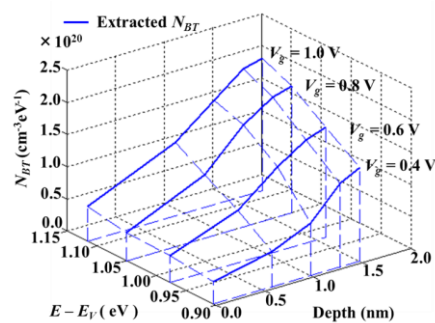


Fig. 2. Extracted oxide traps distribution in energy and space in high-k/InGaAs MOSCAP